



Features

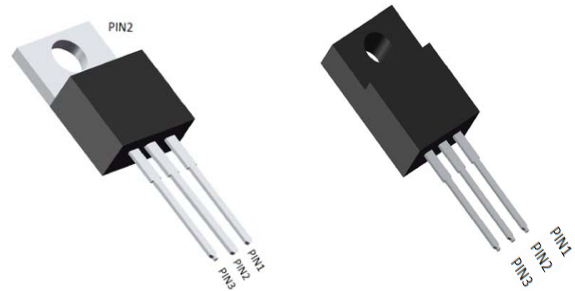
- Adopt FRD chip
- Low forward Voltage drop
- Fast reverse recovery time
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability

Typical Applications

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-220AB ITO-220AB
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked



Maximum Ratings (Ta=25°C Unless otherwise specified)

	V _{RSM} V	V _{RRM} V
MSR3040CT	400	400
MSR3040FCT	400	400

Symbol	Test Conditions	Maximum Ratings	Unit	
I _{FRMS}	T _{VJ} =T _{VJM}	25	A	
I _{FAVM}	T _C =100°C; rectangular, d=0.5	30		
I _{FRM}	t _p <10us; rep. rating, pulse width limited by T _{VJM}	150		
I _{FSM}	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	300 310	A
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	185 195	
I ² t	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	50 50	A ² s
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	36 37	
T _{VJ} T _{VJM} T _{stg}		-55...+175 175 -55...+175	°C	
P _{tot}	T _C =25°C	62	W	
M _d	Mounting torque	0.4...0.6	Nm	
Weight	typical	6	g	



■Electrical Characteristics

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
I_R	$T_{VJ}=25^{\circ}\text{C}; V_R=V_{RRM}$		50	μA
	$T_{VJ}=25^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		25	μA
	$T_{VJ}=125^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		3	mA
V_F	$I_F=15\text{A}; T_{VJ}=150^{\circ}\text{C}$ $T_{VJ}=25^{\circ}\text{C}$		1.05 1.35	V
V_{TO}	For power-loss calculations only		1.12	V
r_T	$T_{VJ}=T_{VJM}$		23.2	$\text{m}\Omega$
R_{thJC} R_{thCK} R_{thJA}		0.5	2 60	K/W
t_{rr}	$I_F=1\text{A}; -di/dt=50\text{A}/\mu\text{s}; V_R=30\text{V}; T_{VJ}=25^{\circ}\text{C}$	28	35	ns
I_{RM}	$V_R=350\text{V}; I_F=15\text{A}; -di_F/dt=100\text{A}/\mu\text{s}; L \leq 0.05\mu\text{H}; T_{VJ}=100^{\circ}\text{C}$	4	4.4	A

■Thermal Characteristics ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	MSR3040CT/MSR3040FCT
Thermal Resistance	Between junction and case	$R_{\theta J-C}$	$^{\circ}\text{C}/\text{W}$	4.0
	Between junction and Air	$R_{\theta J-A}$	$^{\circ}\text{C}/\text{W}$	50

■Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MSR3040CT/MSR3040FCT	Approximate 1.6	50	1000	5000	Tube

■Characteristics (Typical)

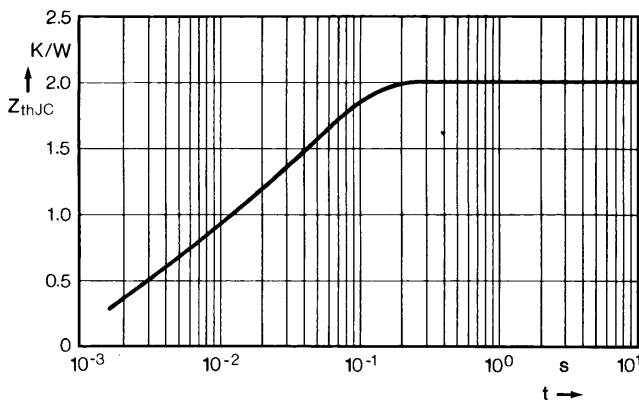


Fig. 7 Transient thermal impedance junction to case.

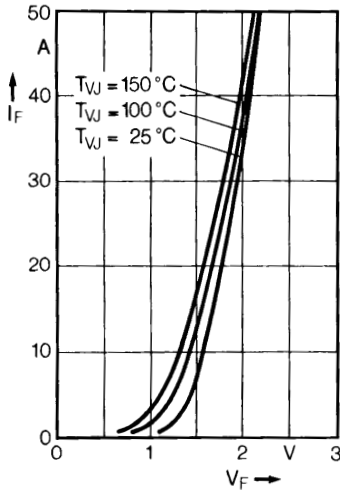


Fig. 1 Forward current versus voltage drop.

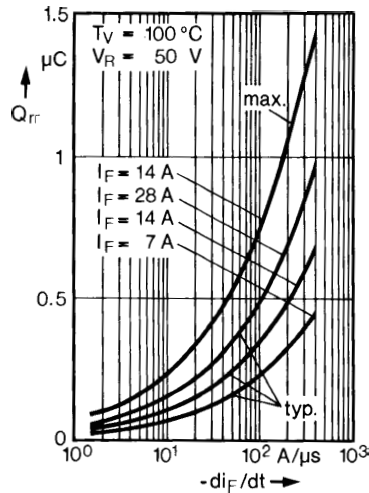


Fig. 2 Recovery charge versus $-di_F/dt$.

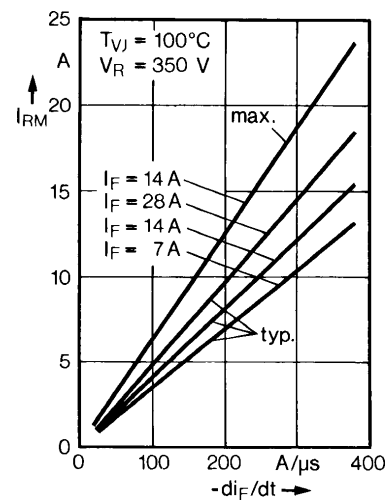


Fig. 3 Peak reverse current versus $-di_F/dt$.

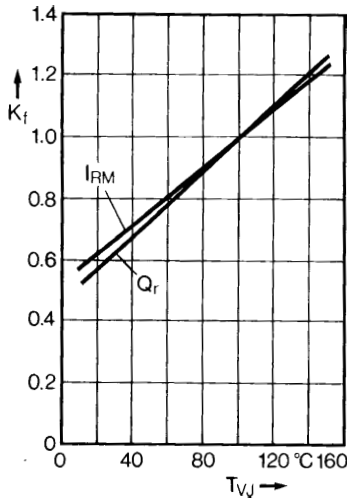


Fig. 4 Dynamic parameters versus junction temperature.

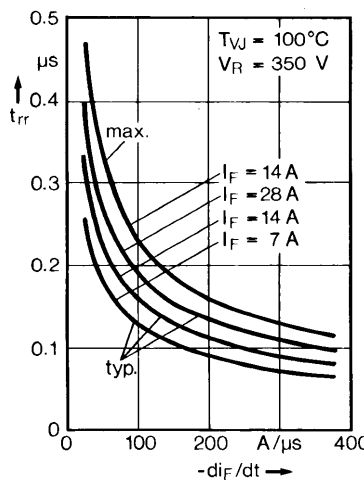


Fig. 5 Recovery time versus $-di_F/dt$.

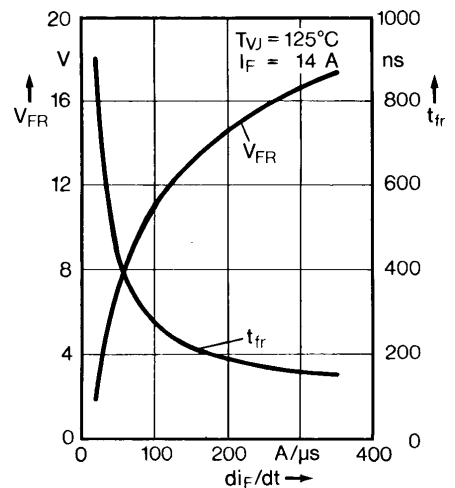
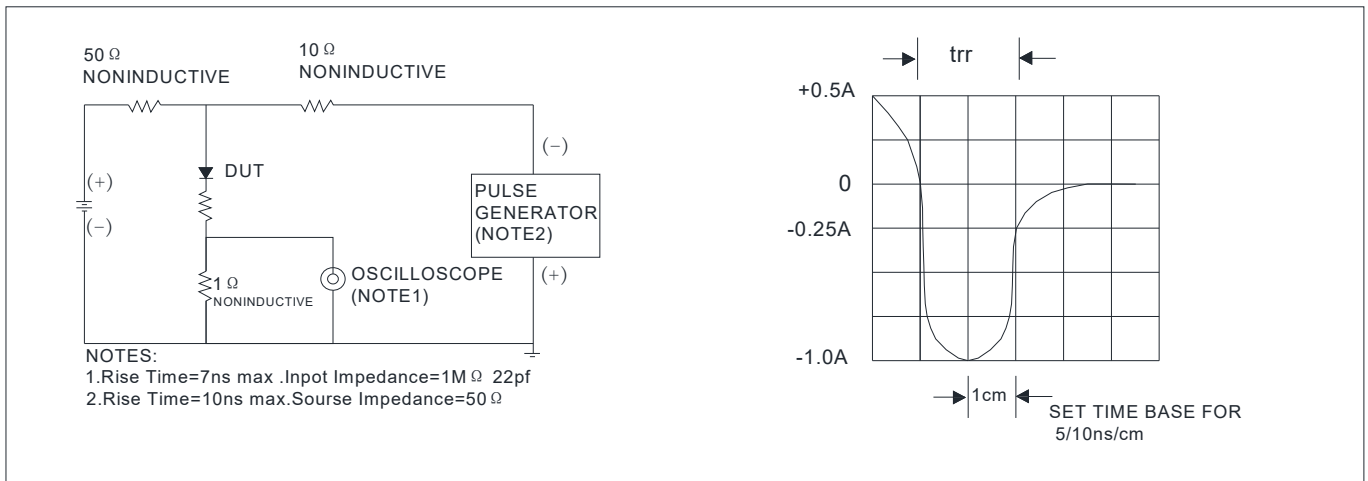


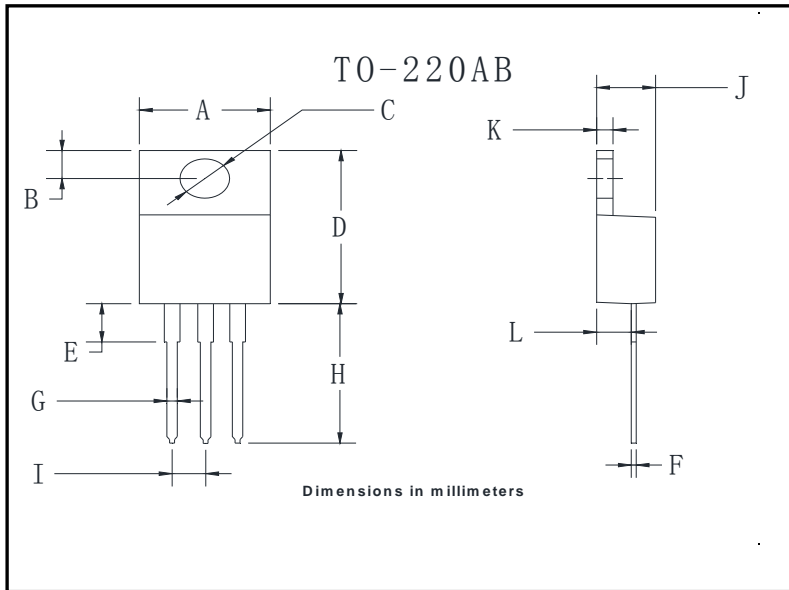
Fig. 6 Peak forward voltage versus di_F/dt .

FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

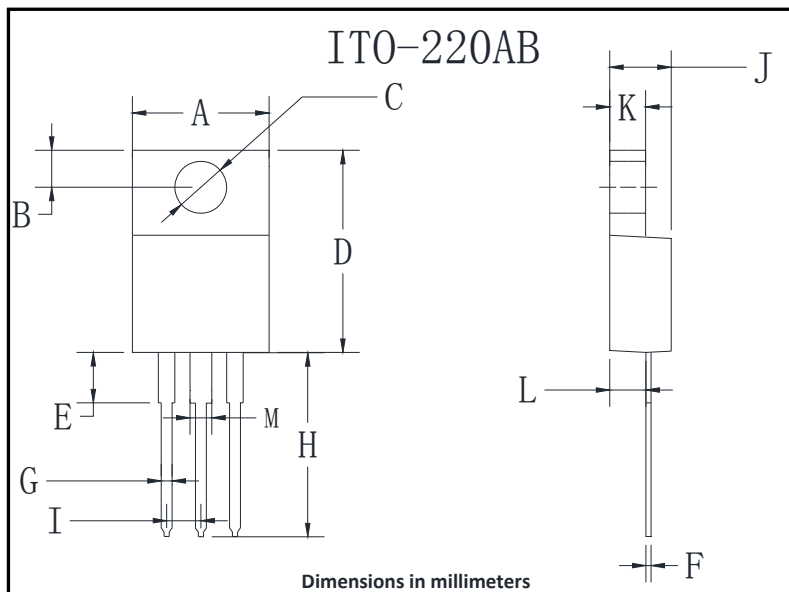




■Outline Dimensions



TO-220AB		
Dim	Min	Max
A	9.5	10.9
B	2.22	3.27
C	3.34	4.31
D	14.5	15.5
E	3.16	4.46
F	0.28	0.64
G	0.68	0.94
H	13.06	14.62
I	2.01	3.07
J	4.04	5.1
K	1.14	1.4
L	2.14	3.19



ITO-220AB		
Dim	Min	Max
A	9.8	10.2
B	2.25	2.75
C	2.95	3.45
D	14.75	15.25
E	3.05	3.95
F	0.45	0.75
G	0.45	0.75
H	13.4	14.2
I	2.35	2.75
J	4.3	4.8
K	2.58	2.82
L	2.58	2.82
M	1.47	1.77